



**EXPEDITED PROCEDURE - EXAMINING GROUP 2814**

**S/N 10/612,328**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	James C Matayabas et al.	Examiner:	Howard Weiss
Serial No.:	10/612,328	Group Art Unit:	2814
Filed:	June 30, 2003	Docket No.:	884.946US1
Title:	<b>POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION</b>		
Assignee:	Intel Corporation	Customer No.:	21186

**AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In response to the Final Office Action mailed March 30, 2005, please amend the application as follows:

14/2/05